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*SPECIFICATION AMENDMENTS*

Replace the paragraph beginning at page 1, line 9 with:

A semiconductor device has leads extending through two sides of a resin package thereof. In a fabrication process of semiconductor device, the leads are formed ~~on-a~~ after the semiconductor device ~~after~~ it is covered with a resin. For example, when gull-wing type leads are formed in a prior art process, a semiconductor device, after being covered with a resin, is put between top and bottom dies for preliminary bending, so that lead parts ~~extended~~ extending from the two sides of the semiconductor device are bent ~~with~~ in a press working. Next, the semiconductor device is put between top and bottom dies ~~for bending~~, so that distal portions of the lead parts are bent in the reverse direction ~~by~~ in a press working. Then, the semiconductor device having the gull-wing leads is put between top and bottom dies for adjustment, ~~so as to have~~ produce a final form.

Replace the paragraph beginning at page 5, line 17 with:

Fig. 4 is a diagram of an example of a device holder;

Replace the paragraph beginning at page 5, line 22 with:

Fig. 7 is a diagram for explaining fabrication of semiconductor ~~device~~ devices of different sizes;

Replace the paragraph beginning at page 6, line 17 with:

Fig. 16 is a diagram for explaining ~~a~~ size of a semiconductor device;

Replace the paragraph beginning at page 6, line 21 with:

Fig. 18 is a diagram for explaining ~~a~~ size of a semiconductor device.